

## **N-Channel 30V Fast Switching MOSFET**

#### **General Description**

The QN3102M6N is a high performance trench N-channel MOSFET which utilizes extremely high cell density to provide low Rdson and gate charge characteristics. It is ideally suited to support synchronous buck converter applications.

The QN3102M6N meets RoHS and Green Product requirements while supporting full function reliability.

#### **Features**

- ✓ Advanced high cell density Trench technology
- ✓ Super Low Gate Charge
- ✓ Green Device Available

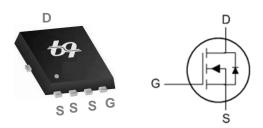
#### **Product Summary**

V <sub>DS</sub>	R <sub>DS(ON)</sub> max (V <sub>GS</sub> =10V)	I <sub>D</sub> (Tc=25 °C)
30V	7.5mΩ	61A

#### **Applications**

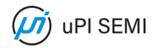
- ✓ High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- ✓ Networking DC-DC Power System
- ✓ Load Switch

### **Pin Configuration**



### **Ordering Information**

Order Number	Package Type	Top Marking		
QN3102M6N	PRPAK5X6	Weekly Code Yearly Code Logo Pin 1 dot Sequence Assembly Code		



## **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	30	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	61	Α
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	38	Α
I <sub>D</sub> @T <sub>A</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	13	Α
ID@T <sub>A</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	10	Α
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	122	Α
EAS	Single Pulse Avalanche Energy <sup>3</sup>	33	mJ
I <sub>AS</sub>	Avalanche Current	25.7	Α
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	44	W
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation <sup>4</sup>	2.0	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C

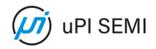
### **Thermal Data**

Symbol	Parameter		Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>		62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>	1	2.8	°C/W



### **N-Channel Electrical Characteristics**

N-Channel Electrical Characteristics: (T <sub>J</sub> =25 °C, unless otherwise noted)						
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	30			V
△BV <sub>DSS</sub> /△T <sub>J</sub>	BVDSS Temperature Coefficient	Reference to 25°C, I <sub>D</sub> =1mA		0.015		V/°C
D) /	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_{D(aval)} = 12.6 \text{ A},$ $T_{case} = 25^{\circ}\text{C}, t_{transient} = 100 \text{ ns}$				V
BV <sub>DSSt</sub>	(transient)		34			
_	Static Drain-Source	V <sub>GS</sub> =10V, I <sub>D</sub> =30A		6.0	7.5	0
R <sub>DS(ON)</sub>	On-Resistance <sup>2</sup>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =15A		8.0	10.4	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	\\ _\\	1.2 2.5		V	
$ riangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA		-3.9		mV/°C
	Duein Course Leakers Courset	V <sub>DS</sub> =24V, V <sub>GS</sub> =0V,T <sub>J</sub> =25°C			1	- uA
IDSS	Drain-Source Leakage Current	V <sub>DS</sub> =24V, V <sub>GS</sub> =0V,T <sub>J</sub> =55°C			5	
Igss	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =15A		26		S
Rg	Gate Resistance	V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1MHz		1.7		Ω
Qg	Total Gate Charge	V <sub>DS</sub> =15V, V <sub>GS</sub> =10V, I <sub>D</sub> =15A		10.5		
Qg	Total Gate Charge			5.0		20
$Q_gs$	Gate-Source Charge	V <sub>DS</sub> =15V, V <sub>GS</sub> =4.5V, I <sub>D</sub> =15A		1.8		nC
$Q_gd$	Gate-Drain Charge			1.7		
t <sub>d(on)</sub>	Turn-On Delay Time			6.0		
t <sub>r</sub>	Rise Time	$V_{DS}$ =15V, $V_{GS}$ =10V, $R_{G}$ =3.3 $\Omega$ ,		44.8		
$t_{\text{d(off)}}$	Turn-Off Delay Time	I <sub>D</sub> =15A		13.5		ns
t <sub>f</sub>	Fall Time			2.5		
Ciss	Input Capacitance	V <sub>DS</sub> =15V, V <sub>GS</sub> =0V, f=1MHz		571		
Coss	Output Capacitance			210		pF
Crss	Reverse Transfer Capacitance			17		



#### **Guaranteed Avalanche Characteristics**

Syml	bol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	S	Single Pulse Avalanche Energy <sup>5</sup>	V <sub>DD</sub> =25V , L=0.1mH , I <sub>AS</sub> =19A	18.05			mJ

### **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current 1,6	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current			61	Α
Іѕм	Pulsed Source Current <sup>2,6</sup>				122	Α
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V, I <sub>S</sub> =1A, T <sub>J</sub> =25°C			1.2	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> =15A, di/dt=100A/μs,		14		nS
Qrr	Reverse Recovery Charge	T <sub>J</sub> =25°C		4		nC

#### Note:

- 1. Test data conducted with surface mount attachment to 1 inch², FR-4 board utilizing 2oz copper
- 2. Pulse Test. Pulse width  $\leq$  300uS, duty cycle  $\leq$  2%
- 3. EAS data is a maximum rating. The test condition is  $V_{DD}$ =25V,  $V_{GS}$ =10V, L=0.1mH
- 4. The power dissipation is limited by a 150°C maximum junction temperature
- 5. The Min. value is 100% EAS tested guarantee
- 6. The data is theoretically the same as  $I_D$  and  $I_{DM}$ . In real applications, it will be limited by total power



### **Typical Characteristics**

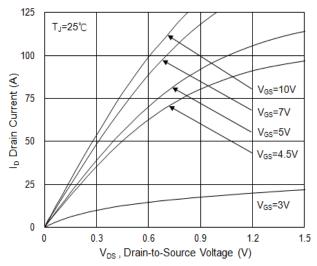


Fig.1: Typical Output Characteristics

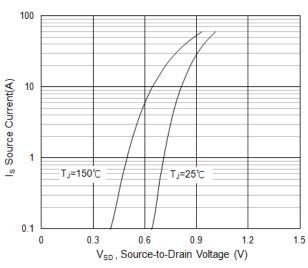


Fig.3: Forward Characteristics of Reverse

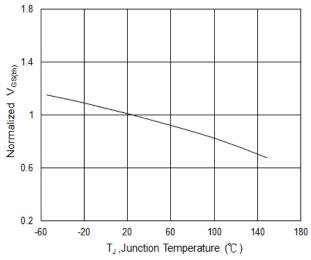


Fig.5: Normalized VGS(th) vs. TJ

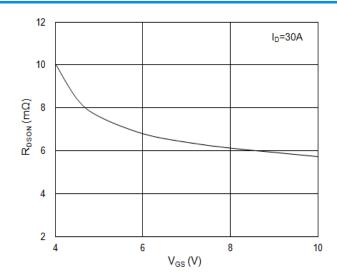


Fig.2: On-Resistance vs. Gate-Source

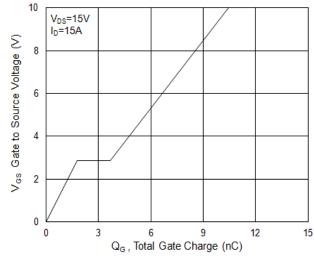


Fig.4: Gate-Charge Characteristics

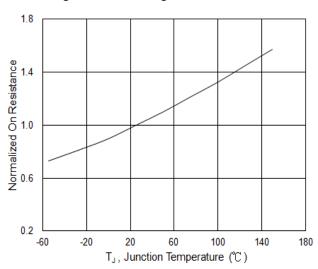


Fig.6: Normalized RDSON vs. TJ



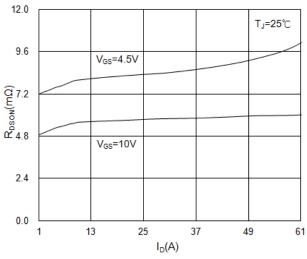


Fig.7: Drain-Source On-State Resistance

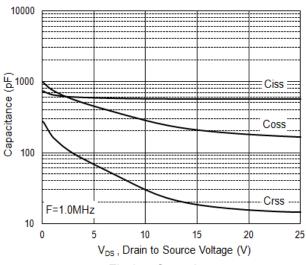


Fig.9: Capacitance

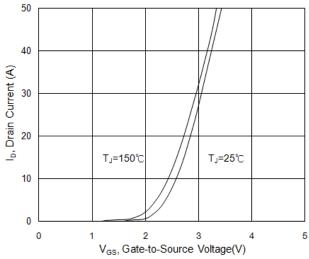


Fig.8: Transfer Characteristics

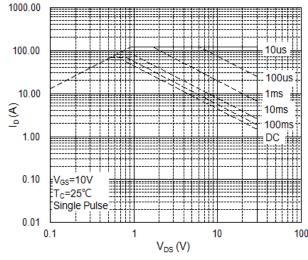


Fig.10: Safe Operating Area

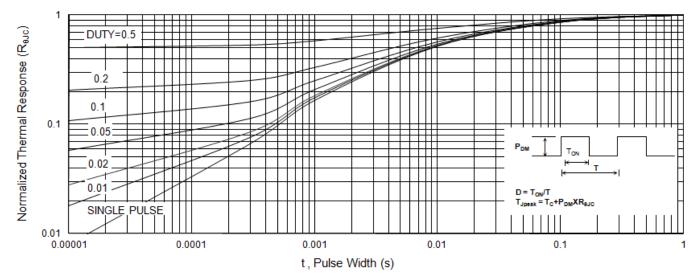


Fig.11: Transient Thermal Impedance



# **Legal Notice**

The contents of this document are provided in connection with uPI Semiconductor Corp. ("uPI") products. uPI makes no representations or warranties with respect to the accuracy or completeness of the contents of this publication and reserves the right to make changes to specifications and product descriptions at any time without notice.

No license, whether express, implied, arising by estoppel or otherwise, to any intellectual property rights, is granted by this publication. Except as provided in uPI's terms and conditions of sale for such products, uPI assumes no liability whatsoever, and uPI disclaims any express or implied warranty relating to sale and/or use of uPI products, including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright or other intellectual property right. uPI products are not designed, intended, authorized or warranted for use as components in systems intended for medical, life-saving, or life sustaining applications. uPI reserves the right to discontinue or make changes to its products at any time without notice.

Copyright© 2019, uPI Semiconductor Corp. All rights reserved. uPI, uPI design logo, and combinations thereof, are trademarks or registered trademarks of uPI Semiconductor Corp.

Other product names used in this publication are for identification purposes only and may be trademarks of their respective companies.



uPI Semiconductor Corp.

9F.,No.5, Taiyuan 1st St. Zhubei City, Hsinchu, Taiwan, R.O.C.

TEL: 886.3.560.1666 FAX: 886.3.560.1888